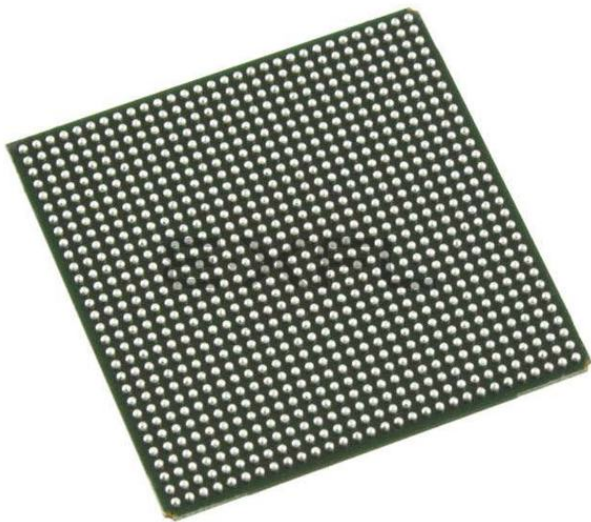




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	6250
Number of Logic Elements/Cells	25000
Total RAM Bits	1966080
Number of I/O	378
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FPBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga25ep1-5f900c

Table 2-9. Supported Input Standards

Input Standard	V _{REF} (Nom.)	V _{CCIO} ¹ (Nom.)	On-chip Termination
Single Ended Interfaces			
LVTTL33 ³	—	3.3	None
LVC MOS 33, 25, 18, 15, 12 ³	—	3.3/2.5/1.8/1.5/1.2	None
PCI33, PCIX33, AGP1X33 ³	—	3.3	None
PCIX15	0.75	1.5 ²	None / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
AGP2X33	1.32	—	None
HSTL18_I, II	0.9	1.8 ²	None / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
HSTL18_III, IV	1.08	1.8 ²	None / V _{CCIO} : 50
HSTL15_I, II	0.75	1.5 ²	None / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
HSTL15_III, IV	0.9	1.5 ²	None / V _{CCIO} : 50
SSTL33_I, II	1.5	3.3	None
SSTL25_I, II	1.25	2.5 ²	None / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
SSTL18_I, II	0.9	1.8 ²	None / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
GTL+, GTL	1.0 / 0.8	1.5 / 1.2 ²	None / V _{CCIO} : 50
Differential Interfaces			
SSTL18D_I, II	—	1.8 ²	None / Diff: 120, 150, 220, 420/ Diff to V _{CMT} : 120, 150, 220, 420 / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
SSTL25D_I, II	—	2.5 ²	None / Diff: 120, 150, 220, 420/ Diff to V _{CMT} : 120, 150, 220, 420 / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
SSTL33D_I, II	—	3.3	None
HSTL15D_I, II	—	1.5 ²	None / Diff: 120, 150, 220, 420/ Diff to V _{CMT} : 120, 150, 220, 420 / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
HSTL18D_I, II	—	1.8 ²	None / Diff: 120, 150, 220, 420/ Diff to V _{CMT} : 120, 150, 220, 420 / V _{CCIO} / 2: 50, 60/ V _{TT} : 60, 75, 120, 210
LVDS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V _{CMT} : 120, 150, 220, 240
Mini-LVDS	—	—	None / Diff: 120, 150 / Diff to V _{CMT} : 120, 150
BLVDS25	—	—	None
MLVDS25	—	—	None
RSDS	—	—	None / Diff: 120, 150, 220, 240/ Diff to V _{CMT} : 120, 150, 220, 240
LVPECL33	—	≤2.5	None / Diff: 120, 150, 220, 240/ Diff to V _{CMT} : 120, 150, 220, 240

1. When not specified V_{CCIO} can be set anywhere in the valid operating range.

2. V_{CCIO} needed for on-chip termination to V_{CCIO}/2 or V_{CCIO} only. V_{CCIO} is not specified for off-chip termination or V_{TT} termination.

3. All ratioed input buffers and dedicated pin input buffers include hysteresis with a typical value of 50mV.

Figure 2-27. Output Termination Schemes

Termination Type	Discrete Off-Chip Solution	Lattice On-Chip Solution
Series termination (controlled output impedance)		
Parallel termination to V_{CCIO} , or parallel driving end		
Parallel termination to $V_{CCIO}/2$ driving end		
Combined series + parallel termination to $V_{CCIO}/2$ at driving end (only series termination moved on-chip)		
Combined series + parallel to $V_{CCIO}/2$ driving end		

VDDAX25 needs to be connected independent of the use of the SERDES. This supply is used to control the SERDES CML I/O regardless of the SERDES being used in the design.

Supported Source Synchronous Interfaces

The LatticeSC devices contain a variety of hardware, such as delay elements, DDR registers and PLLs, to simplify the implementation of Source Synchronous interfaces. Table 2-11 lists Source Synchronous and DDR/QDR standards supported in the LatticeSC. For additional detail refer to technical information at the end of the data sheet.

Table 2-11. Source Synchronous Standards Table¹

Source Synchronous Standard	Clocking	Speeds (MHz)	Data Rate (Mbps)
RapidIO	DDR	500	1000
SPI4.2 (POS-PHY4)/NPSI	DDR	500	1000
SFI4/XSBI	DDR SDR	334 667	667
XGMII	DDR	156.25	312
CSIX	SDR	250	250
QDRII/QDRII+ memory interface	DDR	300	600
DDR memory interface	DDR	240	480
DDRII memory interface	DDR	333	667
RLDRAM memory interface	DDR	400	800

1. Memory width is dependent on the system design and limited by the number of I/Os in the device.

flexiPCS™ (Physical Coding Sublayer Block)

flexiPCS Functionality

The LatticeSC family combines a high-performance FPGA fabric, high-performance I/Os and large embedded RAM in a single industry leading architecture. LatticeSC devices also feature up to 32 channels of embedded SERDES with associated Physical Coding Sublayer (PCS) logic. The flexiPCS logic can be configured to support numerous industry standard high-speed data transfer protocols.

Each channel of flexiPCS logic contains dedicated transmit and receive SERDES for high-speed, full-duplex serial data transfers at data rates up to 3.8 Gbps. The PCS logic in each channel can be configured to support an array of popular data protocols including SONET (STS-12/STS-12c, STS-48/STS-48c, and TFI-5 support of 10 Gbps or above), Gigabit Ethernet (compliant to the IEEE 1000BASE-X specification), 1.02 or 2.04 Gbps Fibre Channel, PCI-Express, and Serial RapidIO. In addition, the protocol based logic can be fully or partially bypassed in a number of configurations to allow users flexibility in designing their own high-speed data interface.

Protocols requiring data rates above 3.8 Gbps can be accommodated by dedicating either one pair or all four channels in one flexiPCS quad block to one data link. One quad can support full-duplex serial data transfers at data rates up to 15.2 Gbps. A single flexiPCS quad can be configured to support 10Gb Ethernet (with a fully compliant XAUI interface), 10Gb Fibre Channel, and x4 PCI-Express and 4x RapidIO.

The flexiPCS also provides bypass modes that allow a direct 8-bit or 10-bit interface from the SERDES to the FPGA logic which can also be geared to run at 1/2 speed for a 16-bit or 20-bit interface to the FPGA logic. Each SERDES pin can be DC coupled independently and can allow for both high-speed and low-speed operation down to DC rates on the same SERDES pin, as required by some Serial Digital Video applications.

The ispLEVER design tools from Lattice support all modes of the flexiPCS. Most modes are dedicated to applications associated with a specific industry standard data protocol. Other more general purpose modes allow a user to define their own operation. With ispLEVER, the user can define the mode for each quad in a design. Nine modes are currently supported by the ispLEVER design flow:

LatticeSC/M Internal Timing Parameters¹ (Continued)

Over Recommended Commercial Operating Conditions at VCC = 1.2V +/- 5%

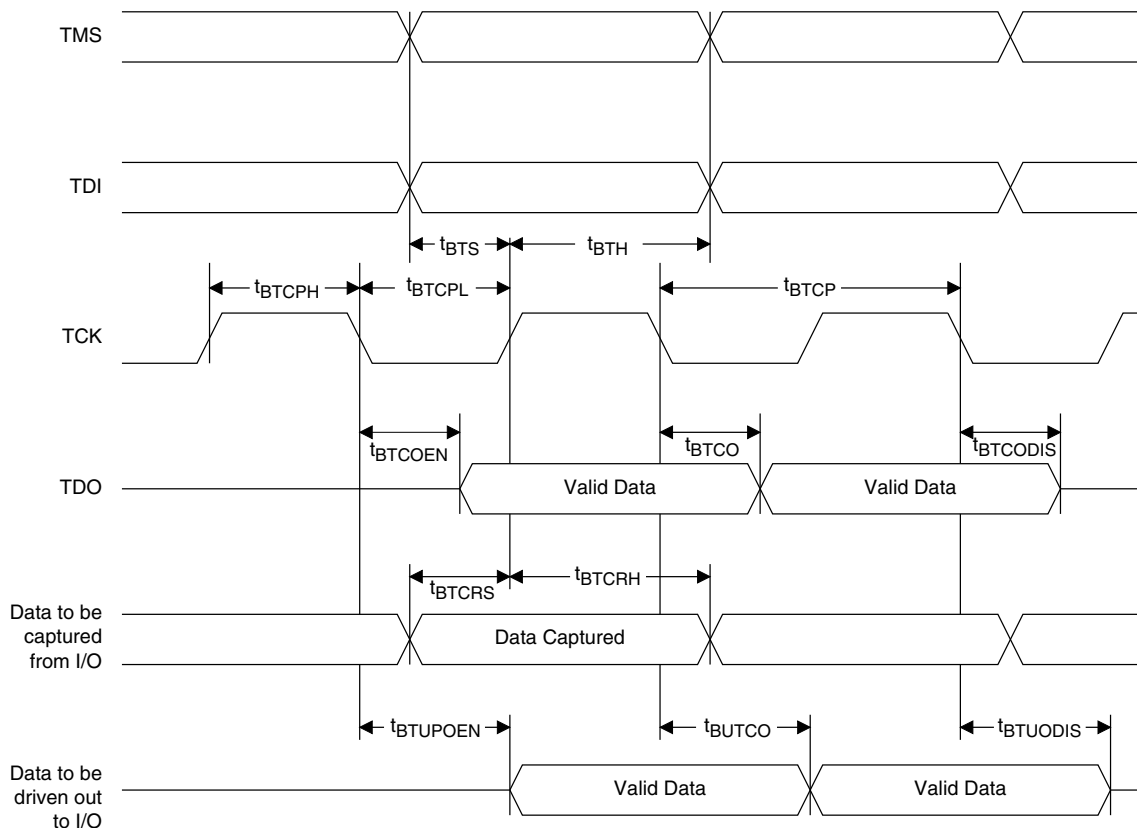
Parameter	Symbol	Description	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
EBR Timing									
t _{CO_EBR}	CK_Q_DEL	Clock (Read) to output from Address or Data	—	1.900	—	2.116	—	2.335	ns
t _{COO_EBR}	CK_Q_DEL	Clock (Write) to output from EBR output Register	0.390	—	0.444	—	0.498	—	ns
t _{SUDATA_EBR}	D_CK_SET	Setup Data to EBR Memory (Write clk)	-0.173	—	-0.192	—	-0.210	—	ns
t _{HDATA_EBR}	D_CK_HLD	Hold Data to EBR Memory (Write clk)	0.276	—	0.305	—	0.335	—	ns
t _{SUADDR_EBR}	A_CK_SET	Setup Address to EBR Memory (Write clk)	-0.165	—	-0.182	—	-0.200	—	ns
t _{HADDR_EBR}	A_CK_HLD	Hold Address to EBR Memory (Write clk)	0.269	—	0.298	—	0.327	—	ns
t _{SUWREN_EBR}	CE_CK_SET	Setup Write/Read Enable to EBR Memory (Write/Read clk)	0.225	—	0.226	—	0.226	—	ns
t _{HWREN_EBR}	CE_CK_HLD	Hold Write/Read Enable to EBR Memory (write/read clk)	0.073	—	0.095	—	0.116	—	ns
t _{SUCE_EBR}	CS_CK_SET	Clock Enable Setup Time to EBR Output Register (Read clk)	0.261	—	0.269	—	0.276	—	ns
t _{HCE_EBR}	CS_CK_HLD	Clock Enable Hold Time to EBR Output Register (Read clk)	0.023	—	0.039	—	0.055	—	ns
t _{RSTO_EBR}	RESET_Q_DEL	Reset To Output Delay Time from EBR Output Register (asynchronous)	—	0.589	—	0.673	—	0.757	ns
Cycle Boosting Timing									
t _{DEL1}	DEL1	Cycle boosting delay 1 applies to PIO, PFU, EBR	—	0.480	—	0.524	—	0.570	ns
t _{DEL2}	DEL2	Cycle boosting delay 2 applies to PIO, PFU, EBR	—	0.922	—	1.005	—	1.090	ns
t _{DEL3}	DEL3	Cycle boosting delay 3 applies to PIO, PFU, EBR	—	1.366	—	1.488	—	1.612	ns

1. Complete timing parameters for a user design will be incorporated when running ispLEVER. This is a sampling of the key timing parameters.

JTAG Port Timing Specifications

Over Recommended Operating Conditions

Symbol	Parameter	Min.	Max.	Units
f_{MAX}		—	25	MHz
t_{BTCP}	TCK [BSCAN] Clock Pulse Width	40	—	ns
t_{BTCPH}	TCK [BSCAN] Clock Pulse Width High	20	—	ns
t_{BTCPL}	TCK [BSCAN] Clock Pulse Width Low	20	—	ns
t_{BTS}	TCK [BSCAN] Setup Time	8	—	ns
t_{BTH}	TCK [BSCAN] Hold Time	10	—	ns
t_{BTRF}	TCK [BSCAN] Rise/Fall Time	50	—	mV/ns
t_{BTCO}	TAP Controller Falling Edge of Clock to Valid Output	—	10	ns
t_{BTCODIS}	TAP Controller Falling Edge of Clock to Valid Disable	—	10	ns
t_{BTCOEN}	TAP Controller Falling Edge of Clock to Valid Enable	—	10	ns
t_{BTCRS}	BSCAN Test Capture Register Setup Time	8	—	ns
t_{BTCRH}	BSCAN Test Capture Register Hold Time	10	—	ns
t_{BUTCO}	BSCAN Test Update Register, Falling Edge of Clock to Valid Output	—	25	ns
t_{BTUODIS}	BSCAN Test Update Register, Falling Edge of Clock to Valid Disable	—	25	ns
t_{BTUPOEN}	BSCAN Test Update Register, Falling Edge of Clock to Valid Enable	—	25	ns

Figure 3-14. JTAG Port Timing Waveforms

Signal Descriptions

Signal Name	I/O	Description
General Purpose		
P[Edge] [Row/Column Number*]_[A/B/C/D]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PIC row or the column of the device on which the PIC exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B/C/D] indicates the PIO within the PIC to which the pad is connected. Some of these user programmable pins are shared with special function pins. These pin when not used as special purpose pins can be programmed as I/Os for user logic. During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
VREF1_x, VREF2_x	—	The reference supply pins for I/O bank x. Any I/O pin in a bank can be assigned as a reference supply pin, but software defaults use designated pin.
NC	—	No connect. NC pins should not be connected to any active signals, VCC or GND.
Non-SERDES Power Supplies		
VCCIOx	—	VCCIO - The power supply pins for I/O bank x. Dedicated pins.
VCC12 ¹	—	1.2V supply for configuration logic, PLLs and SERDES Rx, Tx and PLL. All VCC12 pins must be connected. As VCC12 supplies power for analog circuitry, VCC12 should be quiet and isolated from noisy digital board supplies.
VTT_x	—	Termination voltage for bank x. When VTT termination is not required, or used to provide the common mode termination voltage (VCMT), these pins can be left unconnected on the device. VCMT function is not used in the bank. If the internal or external VCMT function for differential input termination is used, the VTT pins should be unconnected and allowed to float.
GND	—	GND - Ground. Dedicated pins. All grounds must be electrically connected at the board level.
VCC	—	VCC - The power supply pins for core logic. Dedicated pins (1.2V/1.0V).
VCCAUX	—	VCCAUX - Auxiliary power supply pin - powers all differential and referenced input buffers. Dedicated pins (2.5V).
VCCJ	—	VCCJ - The power supply pin for JTAG Test Access Port.
PROBE_VCC	—	VCC signal - Connected to internal VCC node. Can be used for feedback to control an external board power converter. Can be unconnected if not used.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
RESETN		Reset. (Also sent to general routing). During configuration it resets the configuration state machine. After configuration this pin can perform the global set/reset (GSR) functions or can be used as a general input pin.
CFGIRQN	O	MPI Interrupt request active low signal is controlled by system bus interrupt controller and may be sourced from any bus error or MPI configuration error. It can be connected to one of MPC860 IRQ pins.
TSALLN	I	Tristates all I/O.
Configuration Pads (User I/O if not used. Used during sysCONFIG.)		
HDC/SI	O	High During Configuration is output high until configuration is complete. It is used as a control output, indicating that configuration is not complete. For SPI modes, this pin is used to download the read command and initial read address into the Flash memory device on the falling edge of SCK. This pin will be connected to SI of the memory. If the SPI mode is used, the 8-bit instruction code 0x03 will be downloaded followed by a 24-bit starting address of 0x000000 or a non-zero stat address for partial reconfiguration. If the SPIX mode has been selected, the 8-bit instruction captured on D[7:0] at power-up will be shifted in and followed by a 32-bit starting address of 0x000000.
LDCN/SCS	O	Low During Configuration is output low until configuration is complete. It is used as a control output, indicating that configuration is not complete. For SPI modes, this is an active low chip select for Flash memories. It will go active after INITN goes high but before SCK begins. During power up LDCN will be low. Once INITN goes high, LDCN will go high for 100ns-200ns after which time it will go back low and configuration can begin. During the 100ns-200ns period, the read instruction will be latched for SPIX mode.
DOUT	O	Serial data output that can drive the D0/DIN of daisy-chained slave devices. The data-stream from this output will propagate preamble bits of the bitstream to daisy-chained devices. Data out on DOUT changes on the rising edge of CCLK.
QOUT/CEON	O	During daisy-chaining configuration, QOUT is the serial data output that can drive the D0/DIN of daisy-chained slave devices that do not propagate preamble bits. Data out on QOUT changes on the rising edge of CCLK. During parallel-chaining configuration, active low CEON enables the cascaded slave device to receive bitstream data.
RDN	I	Used in the asynchronous peripheral configuration mode. A low on RDN changes D[7:3] into status outputs. WRN and RDN should not be used simultaneously. If they are, the write strobe overrides.
WRN	I	When the FPGA is selected, a low on the write strobe, WRN, loads the data on D[7:0] inputs into an internal data buffer.
CS0N CS1	I	Used in the asynchronous peripheral, slave parallel and MPI modes. The FPGA is selected when CS0N is low and CS1 is high. During configuration, a pull-up is enabled on both except with MPI DMA access control.
A[21:0]	I/O	In master parallel mode, A[21:0] is an output and will address the configuration EPROMs up to 4 MB space. For MPI configuration mode, A[17:0] will be the MPI address MPL_ADDR[31:14], A[19:18] will be the transfer size and A[21:20] will be the burst mode and burst in process.

LFSC/M15 Logic Signal Connections: 256 fpBGA^{1,2} (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
J9	VCC	-	
K8	VCC	-	
F6	VCC12	-	
F11	VCC12	-	
L11	VCC12	-	
L6	VCC12	-	
K7	VCC12	-	
K10	VCC12	-	
F10	VCCAUX	-	
F7	VCCAUX	-	
T1	GND	-	
G11	VCCAUX	-	
K11	VCCAUX	-	
L10	VCCAUX	-	
L9	VCCAUX	-	
L7	VCCAUX	-	
L8	VCCAUX	-	
T16	GND	-	
G6	VCCAUX	-	
K6	VCCAUX	-	
B13	VCCIO1	-	
D11	VCCIO1	-	
D14	VCCIO1	-	
F12	VCCIO2	-	
G15	VCCIO2	-	
K14	VCCIO3	-	
N15	VCCIO3	-	
M11	VCCIO4	-	
P13	VCCIO4	-	
R10	VCCIO4	-	
N6	VCCIO5	-	
P7	VCCIO5	-	
R4	VCCIO5	-	
K2	VCCIO6	-	
N3	VCCIO6	-	
F4	VCCIO7	-	
G3	VCCIO7	-	
D4	VCC12	-	
D7	VCC12	-	
D5	VCC12	-	
D6	VCC12	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).

2. The LatticeSC/M15 in a 256-pin package does not support an MPI interface.

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
F19	PT24A	1	MPI_TEA	PT30A	1	MPI_TEA
J18	PT23D	1	D14/MPI_DATA14	PT28D	1	D14/MPI_DATA14
K18	PT23C	1	DP1/MPI_PAR1	PT28C	1	DP1/MPI_PAR1
E20	PT23B	1	A21/MPI_BURST	PT27B	1	A21/MPI_BURST
F20	PT23A	1	D15/MPI_DATA15	PT27A	1	D15/MPI_DATA15
C23	B_REFCLKP_L	-		B_REFCLKP_L	-	
D23	B_REFCLKN_L	-		B_REFCLKN_L	-	
B23	VCC12	-		VCC12	-	
H21	B_VDDIB3_L	-		B_VDDIB3_L	-	
F21	B_HDINP3_L	-	PCS 361 CH 3 IN P	B_HDINP3_L	-	PCS 361 CH 3 IN P
G21	B_HDINN3_L	-	PCS 361 CH 3 IN N	B_HDINN3_L	-	PCS 361 CH 3 IN N
A21	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P
B21	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N
D21	B_VDDOB3_L	-		B_VDDOB3_L	-	
B22	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N
D22	B_VDDOB2_L	-		B_VDDOB2_L	-	
A22	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P
G22	B_HDINN2_L	-	PCS 361 CH 2 IN N	B_HDINN2_L	-	PCS 361 CH 2 IN N
F22	B_HDINP2_L	-	PCS 361 CH 2 IN P	B_HDINP2_L	-	PCS 361 CH 2 IN P
H22	B_VDDIB2_L	-		B_VDDIB2_L	-	
H24	B_VDDIB1_L	-		B_VDDIB1_L	-	
G23	B_HDINP1_L	-	PCS 361 CH 1 IN P	B_HDINP1_L	-	PCS 361 CH 1 IN P
H23	B_HDINN1_L	-	PCS 361 CH 1 IN N	B_HDINN1_L	-	PCS 361 CH 1 IN N
A24	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P	B_HDOUTP1_L	-	PCS 361 CH 1 OUT P
B24	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N	B_HDOUTN1_L	-	PCS 361 CH 1 OUT N
D24	B_VDDOB1_L	-		B_VDDOB1_L	-	
B25	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N	B_HDOUTN0_L	-	PCS 361 CH 0 OUT N
D25	B_VDDOB0_L	-		B_VDDOB0_L	-	
A25	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P	B_HDOUTP0_L	-	PCS 361 CH 0 OUT P
G25	B_HDINN0_L	-	PCS 361 CH 0 IN N	B_HDINN0_L	-	PCS 361 CH 0 IN N
F25	B_HDINP0_L	-	PCS 361 CH 0 IN P	B_HDINP0_L	-	PCS 361 CH 0 IN P
H25	B_VDDIB0_L	-		B_VDDIB0_L	-	
H26	A_VDDIB3_L	-		A_VDDIB3_L	-	
F26	A_HDINP3_L	-	PCS 360 CH 3 IN P	A_HDINP3_L	-	PCS 360 CH 3 IN P
G26	A_HDINN3_L	-	PCS 360 CH 3 IN N	A_HDINN3_L	-	PCS 360 CH 3 IN N
A26	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P	A_HDOUTP3_L	-	PCS 360 CH 3 OUT P
B26	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N	A_HDOUTN3_L	-	PCS 360 CH 3 OUT N
D26	A_VDDOB3_L	-		A_VDDOB3_L	-	
B27	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N	A_HDOUTN2_L	-	PCS 360 CH 2 OUT N
D27	A_VDDOB2_L	-		A_VDDOB2_L	-	
A27	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P	A_HDOUTP2_L	-	PCS 360 CH 2 OUT P
G27	A_HDINN2_L	-	PCS 360 CH 2 IN N	A_HDINN2_L	-	PCS 360 CH 2 IN N
F27	A_HDINP2_L	-	PCS 360 CH 2 IN P	A_HDINP2_L	-	PCS 360 CH 2 IN P
H27	A_VDDIB2_L	-		A_VDDIB2_L	-	
F29	A_VDDIB1_L	-		A_VDDIB1_L	-	
G28	A_HDINP1_L	-	PCS 360 CH 1 IN P	A_HDINP1_L	-	PCS 360 CH 1 IN P
H28	A_HDINN1_L	-	PCS 360 CH 1 IN N	A_HDINN1_L	-	PCS 360 CH 1 IN N
A29	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P	A_HDOUTP1_L	-	PCS 360 CH 1 OUT P
B29	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N	A_HDOUTN1_L	-	PCS 360 CH 1 OUT N
D29	A_VDDOB1_L	-		A_VDDOB1_L	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
P10	GND	-		GND	-	
P13	GND	-		GND	-	
P15	GND	-		GND	-	
P18	GND	-		GND	-	
P20	GND	-		GND	-	
P24	GND	-		GND	-	
R12	GND	-		GND	-	
R14	GND	-		GND	-	
R16	GND	-		GND	-	
R17	GND	-		GND	-	
R19	GND	-		GND	-	
R21	GND	-		GND	-	
R26	GND	-		GND	-	
R6	GND	-		GND	-	
T15	GND	-		GND	-	
T18	GND	-		GND	-	
T30	GND	-		GND	-	
T4	GND	-		GND	-	
U15	GND	-		GND	-	
U18	GND	-		GND	-	
U29	GND	-		GND	-	
U3	GND	-		GND	-	
V12	GND	-		GND	-	
V14	GND	-		GND	-	
V16	GND	-		GND	-	
V17	GND	-		GND	-	
V19	GND	-		GND	-	
V21	GND	-		GND	-	
V27	GND	-		GND	-	
V7	GND	-		GND	-	
W13	GND	-		GND	-	
W15	GND	-		GND	-	
W18	GND	-		GND	-	
W20	GND	-		GND	-	
W23	GND	-		GND	-	
W9	GND	-		GND	-	
Y12	GND	-		GND	-	
Y14	GND	-		GND	-	
Y19	GND	-		GND	-	
Y21	GND	-		GND	-	
Y30	GND	-		GND	-	
Y4	GND	-		GND	-	
N13	VCC	-		VCC	-	
N15	VCC	-		VCC	-	
N16	VCC	-		VCC	-	
N17	VCC	-		VCC	-	
N18	VCC	-		VCC	-	
N20	VCC	-		VCC	-	
P14	VCC	-		VCC	-	
P16	VCC	-		VCC	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH11	PB57D	4		PB79D	4	
AN13	PB58A	4	PCLKT4_3	PB80A	4	PCLKT4_3
AN12	PB58B	4	PCLKC4_3	PB80B	4	PCLKC4_3
AD14	PB58C	4	PCLKT4_4	PB80C	4	PCLKT4_4
AD15	PB58D	4	PCLKC4_4	PB80D	4	PCLKC4_4
AP13	PB61A	4		PB73A	4	
AP12	PB61B	4		PB73B	4	
AK13	PB61C	4		PB73C	4	
AK12	PB61D	4		PB73D	4	
AP11	PB62A	4		PB83A	4	
AP10	PB62B	4		PB83B	4	
AN11	PB63A	4		PB99A	4	
AN10	PB63B	4		PB99B	4	
AF14	PB63C	4		PB99C	4	
AF13	PB63D	4		PB99D	4	
AM10	PB67A	4		PB101A	4	
AM9	PB67B	4		PB101B	4	
AE14	PB67C	4		PB101C	4	
AE13	PB67D	4		PB101D	4	
AP9	PB69A	4		PB104A	4	
AP8	PB69B	4		PB104B	4	
AK11	PB69C	4		PB104C	4	
AK10	PB69D	4		PB104D	4	
AL10	PB70A	4		PB107A	4	
AL9	PB70B	4		PB107B	4	
AF12	PB70C	4		PB107C	4	
AF11	PB70D	4		PB107D	4	
AN9	PB73A	4		PB109A	4	
AN8	PB73B	4		PB109B	4	
AG11	PB73C	4		PB109C	4	
AG10	PB73D	4		PB109D	4	
AP7	PB74A	4		PB111A	4	
AP6	PB74B	4		PB111B	4	
AG13	PB74C	4		PB111C	4	
AG12	PB74D	4		PB111D	4	
AN7	PB75A	4		PB113A	4	
AN6	PB75B	4		PB113B	4	
AK9	PB75C	4		PB113C	4	
AK8	PB75D	4		PB113D	4	
AP5	PB77A	4		PB115A	4	
AP4	PB77B	4		PB115B	4	
AD11	PB77C	4		PB115C	4	
AE11	PB77D	4		PB115D	4	
AM7	PB78A	4		PB117A	4	
AM6	PB78B	4		PB117B	4	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AJ9	PB78C	4		PB117C	4	
AJ8	PB78D	4		PB117D	4	
AP3	PB79A	4		PB119A	4	
AN3	PB79B	4		PB119B	4	
AF10	PB79C	4		PB119C	4	
AE10	PB79D	4		PB119D	4	
AL7	PB81A	4		PB121A	4	
AL6	PB81B	4		PB121B	4	
AK7	PB81C	4		PB121C	4	
AK6	PB81D	4		PB121D	4	
AN5	PB82A	4		PB123A	4	
AN4	PB82B	4		PB123B	4	
AH9	PB82C	4	VREF1_4	PB123C	4	VREF1_4
AH8	PB82D	4		PB123D	4	
AM3	PB83A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D	PB124A	4	LRC_DLLT_IN_C/LRC_DLLT_FB_D
AM4	PB83B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D	PB124B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
AG9	PB83C	4		PB124C	4	
AG8	PB83D	4		PB124D	4	
AN2	PB85A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B	PB125A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B
AM2	PB85B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B	PB125B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B
AJ6	PB85C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C	PB125C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C
AH6	PB85D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C	PB125D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C
AF7	PROBE_VCC	-		PROBE_VCC	-	
AF8	PROBE_GND	-		PROBE_GND	-	
AG7	PR71D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A	PR95D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A
AG6	PR71C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A	PR95C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A
AL4	PR71B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E	PR95B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
AL3	PR71A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E	PR95A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
AD10	PR70D	3		PR94D	3	
AD9	PR70C	3		PR94C	3	
AH4	PR70B	3		PR94B	3	
AJ4	PR70A	3		PR94A	3	
AK5	PR69D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F	PR93D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F
AJ5	PR69C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F	PR93C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F
AM1	PR69B	3		PR93B	3	
AL1	PR69A	3		PR93A	3	
AH5	PR67D	3		PR91D	3	
AG5	PR67C	3		PR91C	3	
AL2	PR67B	3		PR91B	3	
AK2	PR67A	3		PR91A	3	
AB9	PR66D	3		PR90D	3	
AC9	PR66C	3		PR90C	3	
AH1	PR66B	3		PR90B	3	
AG1	PR66A	3		PR90A	3	
AE8	PR65D	3	VREF2_3	PR89D	3	VREF2_3

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
W13	VCCAUX	-		VCCAUX	-	
W22	VCCAUX	-		VCCAUX	-	
Y21	GND	-		GND	-	
Y25	GND	-		GND	-	
C18	VCCIO1	-		VCCIO1	-	
D17	VCCIO1	-		VCCIO1	-	
F16	VCCIO1	-		VCCIO1	-	
G19	VCCIO1	-		VCCIO1	-	
J20	VCCIO1	-		VCCIO1	-	
K12	VCCIO1	-		VCCIO1	-	
K15	VCCIO1	-		VCCIO1	-	
L23	VCCIO1	-		VCCIO1	-	
Y9	GND	-		GND	-	
J9	VCCIO1	-		VCCIO1	-	
E3	VCCIO2	-		VCCIO2	-	
G6	VCCIO2	-		VCCIO2	-	
H4	VCCIO2	-		VCCIO2	-	
K7	VCCIO2	-		VCCIO2	-	
L3	VCCIO2	-		VCCIO2	-	
M11	VCCIO2	-		VCCIO2	-	
N6	VCCIO2	-		VCCIO2	-	
P4	VCCIO2	-		VCCIO2	-	
R9	VCCIO2	-		VCCIO2	-	
AA3	VCCIO3	-		VCCIO3	-	
AB7	VCCIO3	-		VCCIO3	-	
AC10	VCCIO3	-		VCCIO3	-	
AD4	VCCIO3	-		VCCIO3	-	
AE6	VCCIO3	-		VCCIO3	-	
AG3	VCCIO3	-		VCCIO3	-	
AK4	VCCIO3	-		VCCIO3	-	
T7	VCCIO3	-		VCCIO3	-	
U3	VCCIO3	-		VCCIO3	-	
V4	VCCIO3	-		VCCIO3	-	
W6	VCCIO3	-		VCCIO3	-	
Y10	VCCIO3	-		VCCIO3	-	
AD12	VCCIO4	-		VCCIO4	-	
AF15	VCCIO4	-		VCCIO4	-	
AF9	VCCIO4	-		VCCIO4	-	
AH10	VCCIO4	-		VCCIO4	-	
AH16	VCCIO4	-		VCCIO4	-	
AJ13	VCCIO4	-		VCCIO4	-	
AJ7	VCCIO4	-		VCCIO4	-	
AL14	VCCIO4	-		VCCIO4	-	
AL8	VCCIO4	-		VCCIO4	-	
AM11	VCCIO4	-		VCCIO4	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA^{1, 2}

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
H34	PL40B	7	
M32	PL53A	7	
N32	PL53B	7	
P28	PL53C	7	
R28	PL53D	7	
J34	PL55A	7	
K34	PL55B	7	
P30	PL55C	7	
R30	PL55D	7	
W34	PL73A	6	
Y34	PL73B	6	
W32	PL75A	6	
Y32	PL75B	6	
AA34	PL78A	6	
AB34	PL78B	6	
AC34	PL81A	6	
AD34	PL81B	6	
Y30	PL82A	6	
AA30	PL82B	6	
AB33	PL83A	6	
AC33	PL83B	6	
AC2	PR83B	3	
AB2	PR83A	3	
AA5	PR82B	3	
Y5	PR82A	3	
AD1	PR81B	3	
AC1	PR81A	3	
AB1	PR78B	3	
AA1	PR78A	3	
Y3	PR75B	3	
W3	PR75A	3	
Y1	PR73B	3	
W1	PR73A	3	
R5	PR55D	2	
P5	PR55C	2	
K1	PR55B	2	
J1	PR55A	2	
R7	PR53D	2	
P7	PR53C	2	
N3	PR53B	2	
M3	PR53A	2	
H1	PR40B	2	
G1	PR40A	2	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2}

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
G34	A_REFCLKP_L	-		A_REFCLKP_L	-	
H34	A_REFCLKN_L	-		A_REFCLKN_L	-	
N30	VCC12	-		VCC12	-	
H33	RESP_ULC	-		RESP_ULC	-	
P25	RESETN	1		RESETN	1	
P26	TSALLN	1		TSALLN	1	
P31	DONE	1		DONE	1	
P23	INITN	1		INITN	1	
P30	M0	1		M0	1	
P22	M1	1		M1	1	
P24	M2	1		M2	1	
R22	M3	1		M3	1	
J37	PL16A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B	PL15A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
J38	PL16B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B	PL15B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
P32	PL16C	7		PL15C	7	
R32	PL16D	7		PL15D	7	
G40	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
H40	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
N33	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A	PL17C	7	ULC_PLLT_IN_B/ULC_PLLT_FB_A
P33	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A	PL17D	7	ULC_PLLC_IN_B/ULC_PLLC_FB_A
G41	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C	PL18A	7	ULC_DLLT_IN_D/ULC_DLLT_FB_C
H41	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C	PL18B	7	ULC_DLLC_IN_D/ULC_DLLC_FB_C
T29	PL18C	7		PL18C	7	
U29	PL18D	7	VREF2_7	PL18D	7	VREF2_7
G42	PL20A	7		PL19A	7	
H42	PL20B	7		PL19B	7	
M34	PL20C	7		PL19C	7	
M35	PL20D	7		PL19D	7	
K37	PL21A	7		PL26A	7	
L37	PL21B	7		PL26B	7	
N34	PL21C	7		PL26C	7	
P34	PL21D	7		PL26D	7	
K38	PL22A	7		PL30A	7	
L38	PL22B	7		PL30B	7	
T33	PL22C	7		PL30C	7	
R33	PL22D	7		PL30D	7	
J41	PL24A	7		PL34A	7	
K41	PL24B	7		PL34B	7	
U31	PL24C	7		PL34C	7	
V31	PL24D	7		PL34D	7	
K42	PL25A	7		PL38A	7	
J42	PL25B	7		PL38B	7	
J36	PL25C	7		PL38C	7	
K36	PL25D	7		PL38D	7	
N38	PL26A	7		PL40A	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
P38	PL26B	7		PL40B	7	
N35	PL26C	7		PL40C	7	
N36	PL26D	7		PL40D	7	
N39	PL29A	7		PL43A	7	
P39	PL29B	7		PL43B	7	
R34	PL29C	7	VREF1_7	PL43C	7	VREF1_7
T34	PL29D	7	DIFFR_7	PL43D	7	DIFFR_7
L41	PL30A	7		PL44A	7	
M41	PL30B	7		PL44B	7	
W29	PL30C	7		PL44C	7	
Y29	PL30D	7		PL44D	7	
L42	PL31A	7		PL45A	7	
M42	PL31B	7		PL45B	7	
U32	PL31C	7		PL45C	7	
V32	PL31D	7		PL45D	7	
R37	PL33A	7		PL47A	7	
T37	PL33B	7		PL47B	7	
M36	PL33C	7		PL47C	7	
M37	PL33D	7		PL47D	7	
P40	PL34A	7		PL48A	7	
N40	PL34B	7		PL48B	7	
R35	PL34C	7		PL48C	7	
T35	PL34D	7		PL48D	7	
N41	PL35A	7		PL49A	7	
P41	PL35B	7		PL49B	7	
V33	PL35C	7		PL49C	7	
U33	PL35D	7		PL49D	7	
R38	PL37A	7		PL51A	7	
T38	PL37B	7		PL51B	7	
R36	PL37C	7		PL51C	7	
T36	PL37D	7		PL51D	7	
N42	PL38A	7		PL52A	7	
P42	PL38B	7		PL52B	7	
Y31	PL38C	7		PL52C	7	
AA31	PL38D	7		PL52D	7	
U37	PL39A	7		PL53A	7	
V37	PL39B	7		PL53B	7	
U34	PL39C	7		PL53C	7	
V34	PL39D	7		PL53D	7	
U39	PL41A	7		PL55A	7	
T39	PL41B	7		PL55B	7	
V35	PL41C	7		PL55C	7	
W35	PL41D	7		PL55D	7	
R41	PL42A	7		PL56A	7	
T41	PL42B	7		PL56B	7	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
D1	A_HDINN0_R	-	PCS 3E0 CH 0 IN N	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
F1	VCC12	-		VCC12	-	
A3	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P
E1	A_VDDOB0_R	-		A_VDDOB0_R	-	
B3	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N	A_HDOUTN0_R	-	PCS 3E0 CH 0 OUT N
C2	A_VDDOB1_R	-		A_VDDOB1_R	-	
A4	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N	A_HDOUTN1_R	-	PCS 3E0 CH 1 OUT N
B2	VCC12	-		VCC12	-	
B4	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P	A_HDOUTP1_R	-	PCS 3E0 CH 1 OUT P
E3	A_HDINN1_R	-	PCS 3E0 CH 1 IN N	A_HDINN1_R	-	PCS 3E0 CH 1 IN N
D3	A_HDINP1_R	-	PCS 3E0 CH 1 IN P	A_HDINP1_R	-	PCS 3E0 CH 1 IN P
M10	VCC12	-		VCC12	-	
E2	A_VDDIB1_R	-		A_VDDIB1_R	-	
J11	VCC12	-		VCC12	-	
M11	A_VDDIB2_R	-		A_VDDIB2_R	-	
D4	A_HDINP2_R	-	PCS 3E0 CH 2 IN P	A_HDINP2_R	-	PCS 3E0 CH 2 IN P
E4	A_HDINN2_R	-	PCS 3E0 CH 2 IN N	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
K9	VCC12	-		VCC12	-	
A5	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
D2	A_VDDOB2_R	-		A_VDDOB2_R	-	
B5	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
L10	A_VDDOB3_R	-		A_VDDOB3_R	-	
B6	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
G6	VCC12	-		VCC12	-	
A6	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
E5	A_HDINN3_R	-	PCS 3E0 CH 3 IN N	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
D5	A_HDINP3_R	-	PCS 3E0 CH 3 IN P	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
K12	VCC12	-		VCC12	-	
L13	A_VDDIB3_R	-		A_VDDIB3_R	-	
N14	VCC12	-		VCC12	-	
F9	B_VDDIB0_R	-		B_VDDIB0_R	-	
D6	B_HDINP0_R	-	PCS 3E1 CH 0 IN P	B_HDINP0_R	-	PCS 3E1 CH 0 IN P
E6	B_HDINN0_R	-	PCS 3E1 CH 0 IN N	B_HDINN0_R	-	PCS 3E1 CH 0 IN N
J8	VCC12	-		VCC12	-	
B7	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P
G4	B_VDDOB0_R	-		B_VDDOB0_R	-	
A7	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N
K8	B_VDDOB1_R	-		B_VDDOB1_R	-	
A8	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N
L9	VCC12	-		VCC12	-	
B8	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P
E7	B_HDINN1_R	-	PCS 3E1 CH 1 IN N	B_HDINN1_R	-	PCS 3E1 CH 1 IN N
D7	B_HDINP1_R	-	PCS 3E1 CH 1 IN P	B_HDINP1_R	-	PCS 3E1 CH 1 IN P
F10	VCC12	-		VCC12	-	
K13	B_VDDIB1_R	-		B_VDDIB1_R	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA^{1, 2} (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH27	VCCAUX	-		VCCAUX	-	
AH29	VCCAUX	-		VCCAUX	-	
AJ14	VCCAUX	-		VCCAUX	-	
AJ15	VCCAUX	-		VCCAUX	-	
AJ28	VCCAUX	-		VCCAUX	-	
AJ29	VCCAUX	-		VCCAUX	-	
P14	VCCAUX	-		VCCAUX	-	
P15	VCCAUX	-		VCCAUX	-	
P28	VCCAUX	-		VCCAUX	-	
P29	VCCAUX	-		VCCAUX	-	
R14	VCCAUX	-		VCCAUX	-	
R16	VCCAUX	-		VCCAUX	-	
R17	VCCAUX	-		VCCAUX	-	
R18	VCCAUX	-		VCCAUX	-	
R19	VCCAUX	-		VCCAUX	-	
R20	VCCAUX	-		VCCAUX	-	
R23	VCCAUX	-		VCCAUX	-	
R24	VCCAUX	-		VCCAUX	-	
R25	VCCAUX	-		VCCAUX	-	
R26	VCCAUX	-		VCCAUX	-	
R27	VCCAUX	-		VCCAUX	-	
R29	VCCAUX	-		VCCAUX	-	
T15	VCCAUX	-		VCCAUX	-	
T28	VCCAUX	-		VCCAUX	-	
U15	VCCAUX	-		VCCAUX	-	
U28	VCCAUX	-		VCCAUX	-	
V15	VCCAUX	-		VCCAUX	-	
V28	VCCAUX	-		VCCAUX	-	
W15	VCCAUX	-		VCCAUX	-	
W28	VCCAUX	-		VCCAUX	-	
Y15	VCCAUX	-		VCCAUX	-	
Y28	VCCAUX	-		VCCAUX	-	
F3	VCCIO1	-		VCCIO1	-	
F39	VCCIO1	-		VCCIO1	-	
G35	VCCIO1	-		VCCIO1	-	
G8	VCCIO1	-		VCCIO1	-	
L19	VCCIO1	-		VCCIO1	-	
L24	VCCIO1	-		VCCIO1	-	
M16	VCCIO1	-		VCCIO1	-	
M27	VCCIO1	-		VCCIO1	-	
N11	VCCIO1	-		VCCIO1	-	
N32	VCCIO1	-		VCCIO1	-	
AA4	VCCIO2	-		VCCIO2	-	
H7	VCCIO2	-		VCCIO2	-	
J4	VCCIO2	-		VCCIO2	-	

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FC1152C ¹	-6	Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FC1152C ¹	-5	Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FF1152C	-6	Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FF1152C	-5	Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FC1704C ¹	-6	Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FC1704C ¹	-5	Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-6FF1704C	-6	Organic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FF1704C	-5	Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per [PCN #01A-10](#).

Date	Version	Section	Change Summary
September 2007	01.7	Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.
November 2007	01.8	Ordering Information	Removed -7 speed grade information for 115K LUT devices in the Ordering Information tables.
January 2008	01.9	Introduction	Corrections/Additions to memory controller list (Tables 1-2).
		Architecture	AIL Overview – Modified power used by AIL block.
			PURESPEED I/O Buffer Banks – Modified VTT termination info. Added info about complimentary drivers for all banks.
			Supported Source Synchronous Interfaces – Modified data for DDRII in Table 2-11.
		DC and Switching Characteristics	Recommended Operating Conditions – Changed footnote 3.
			Initialization and Standby Supply Current – Inserted a paragraph with info regarding the table. Also updated the table.
			Typical Building Block Function Performance – Added VCC=1.2V=1.2V+/-5% above Pin to Pin Performance table.
			LatticeSC External Switching Characteristics – Added VCC=1.2V=1.2V+/-5% above table. Reworded footnote 3.
			LatticeSC Family Timing Adders – Added VCC=1.2V=1.2V+/-5% above table.
			LatticeSC Internal Timing Parameters – Added VCC=1.2V=1.2V+/-5% above table. Reworded footnote 1.
			GSR Timing – Added a new table for Internal System Bus Timing after GSR Timing.
			LatticeSC sysCONFIG Port Timing – Corrected sysCONFIG SPI Port information.
		Pinout Information	Signal Descriptions – Modified info for VTT_x, PROBE_VCC, and PROBE_GND. Modified info for [LOC]_DLL[T,C]_IN[C,D,E,F].
		Supplemental Information	Updated list of technical notes, added reference to LatticeSC/M flexiPCS Data Sheet.
March 2008	02.0	DC and Switching Characteristics	Updated Internal Timing Parameters table.
			Updated Read Mode timing diagram.
			Updated Read Mode with Input Registers Only timing diagram.
June 2008	02.1	—	Data sheet status changed from preliminary to final.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
		DC and Switching Characteristics	Updated LatticeSC/M External Switching Characteristics table.
			Updated LatticeSC/M Internal Timing Parameters table.
December 2008	02.2	Architecture	Removed Read-Before-Write sysMEM EBR mode.
			Output/Tristate DDR/Shift Register Block Diagram - corrected connection to POS.
			DC and Switching Characteristics table - updated data for t_{SUI_PIO} .
		Multiple	Added T_R , T_F parameter to PURESPEED I/O Differential Electrical Characteristics (LVDS) table.
January 2010	02.3	Multiple	Removed references to HyperTransport throughout the data sheet.
		Introduction	Updated per PCN #01A-10 (ceramic fcBGA conversion to organic fcBGA for the 1152-ball and 1704-ball fcBGA packages) and PCN #02A-10 (1020-ball organic fcBGA conversion to 1020-ball organic fcBGA revision 2 package).
		Ordering Information	